

Semiconductor Chip Arrangement and a Method for Its Production

ABSTRACT OF THE DISCLOSURE

The present invention relates to a semiconductor chip arrangement in which signals are interchanged between semiconductor substrates via contact areas in the side surfaces of the semiconductor substrates rather than via a mount element. The contact areas may be used as horizontally connecting contacts between semiconductor substrates which are located alongside one another, or else as vertically connecting contacts between semiconductor substrates which lie one on top of the other, thus saving connecting lines, running on the mount element, between the semiconductor substrates.